	Typ	L #	Hits	S arch Text	DBs
1	BRS	L1	6418	pad n ar5 (air r spac)	USPAT
2	BRS	L2	0	1 sam ((wafer adj l vel adj package) r wlp)	USPAT
3	BRS	L3	61	1 same (interconnection or interconnect)	USPAT
4	BRS	L4	10372	pad near15 (air or space)	USPAT
5	BRS	L5	32	4 same (solder adj2 (balls or ball))	USPAT
6	BRS	L6	3762	(ball adj grid adj array) or bga	USPAT
7	BRS	L7	15	4 same 6	USPAT
8	BRS	L8	1754	6 same (solder adj2 (balls or ball))	USPAT
9	BRS	L9	897	8 and (stresses or stress or expansion or contraction or resilient)	USPAT

	Type	L #	Hits	S arch Text	DBs
1	BRS	L1	5106	pad near5 (air or spac)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L2	0	1 same (solder adj2 (balls or ball))	USPAT
3	BRS	L3	14	1 same (solder adj2 (balls or ball))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB